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### (54) COMPONENT CARRIER WITH PHOTOSENSITIVE ADHESION PROMOTER AND METHOD OF MANUFACTURING THE **SAME**

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#### ABSTRACT (57)

A component carrier which comprises a stack comprising at least one electrically conductive layer structure and/or at least one electrically insulating layer structure, and a photosensitive adhesion promoter on or above the stack, wherein only a sub-portion of the photosensitive adhesion promoter is photoactivated, and electrically conductive material selectively on said sub-portion of the photosensitive adhesion promoter.

